



MICRO-FAZE® A

Dry-to-touch Thermal Pad

Product Code: 52046

TECHNICAL DATA SHEET



THERMALLY CONDUCTIVE INTERFACE MATERIAL

Product Description

MICRO-FAZE® A is a dry-to-touch thermal interface pad formulated with non-silicone thermal grease. It was developed by AOS to offer the low thermal resistance in a thermal interface without the mess of grease. MICRO-FAZE A is a die-cut aluminum foil substrate coated on both sides with specially formulated thermal grease that is naturally tacky but dry to the touch. MICRO-FAZE A is **non-wax-based** and offers low pressure and temperature heat transfer properties.



Product Features & Benefits

- MICRO-FAZE A retains all the unique advantages of thermal grease but in the form of a thermal interface film.
- **Minimum force** (< 15 psi) is required to achieve total interface contact.
- MICRO-FAZE allows for **total “wetting action”** to fill all microscopic surface voids **without changing phase**.
- Unlike phase change materials, **heat transfer starts at 25°C** or lower, making MICRO-FAZE A an excellent choice for cold plate applications.
- Offers maximum heat transfer capability for power components.
- Excellent replacement for phase change materials and silicone pads.
- MICRO-FAZE A is a **“drop-in-place”** product that is easy to use and handle in a manufacturing environment.
- **Naturally tacky** – no adhesive, fiberglass or other non-conductive material is used that may penalize thermal resistance.
- **Thixotropic** nature prevents run out.
- The material will withstand an operating temperature range of up to 200 °C for brief periods.

Available Configurations

MICRO-FAZE A is available in rolls and can be die-cut to exact specifications.

Major Applications

- Power modules, IGBTs, DC-DC converter modules, solid state relays, diodes, power MOSFETs, RF components and thermoelectric modules.
- Microprocessors, multichip modules, ASICs and other digital components.
- Power amplifiers, large area applications for power supplies and other custom enclosure heat dissipating surfaces.

Typical Properties

Physical Properties	A4	A6
Substrate	Aluminum	Aluminum
Substrate Thickness	0.002in.	0.002in.
Compound Thickness (per side)	0.001in.	0.002in.
Total Thickness	0.004in.	0.006in.
Thermal Properties		
Thermal Resistance @ 70 psi & 36 °C	0.144 °C-in ² / W	0.183 °C-in ² / W
Thermal Conductivity @ 36 °C (ASTM D-5470-06)	3.0 W/m-K	2.8 W/m-K

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